SECTION I—SPECIFICATION AMENDMENTS

Please amend the specification as indicated below:

1. Please replace paragraph [0025] with the following amended paragraph:

[0025] The magnetic layer 118 may be disposed on the DSC, according to one embodiment, during DSC manufacturing, such as using a conventional printing method. According to embodiments, magnetic layer is selected to provide a magnetic force MF that produces a torque larger than a torque produced by uneven surface tension forces STF of the two solder deposits 22, while at the same time having minimal impact on the performance of circuits on the substrate or on the SMT component. Preferably, a magnetic material is selected having a ~~Courier~~ Curie temperature that is slightly higher than the reflow peak temperature range of the solder to undergo reflow. For example, the ~~Courier~~ Curie temperature of the magnetic material chosen may be between about 10 degrees Celsius to about 20 degrees Celsius higher than a reflow peak temperature range of the solder. In such a case, where lead-containing solder is used, the peak reflow temperature range would be between about 210 degrees Celsius and about 220 degrees Celsius, in which case the ~~Courier~~ Curie temperature range acceptable for the purposes of embodiments would be between about 220 degrees Celsius and about 240 degrees Celsius. In addition, where lead-free solder is used, the peak reflow temperature range would be between about 240 degrees Celsius and about 250 degrees Celsius, in which case the ~~Courier~~ Curie temperature range acceptable for the purposes of embodiments would be between about 260 degrees Celsius and about 270 degrees Celsius. A magnetic material with a ~~Courier~~ Curie temperature below the reflow peak temperature range could substantially lose its magnetic properties during reflow, thus disadvantageously leading

to an effective disappearance of a counteracting magnetic force MF between the SMT component such as DSC 116, and the underlying substrate. More preferably, a magnetic material is selected that exhibits a remanence adapted to have a minimum impact on a performance of circuits within the SMT component or within the substrate. A selection of magnetic materials based on remanence and its impact on circuit performance becomes especially important in the case of circuits having higher frequencies, such as frequencies equal to or above about 2 GHz, as in the case of a CPU. On the other hand, a magnetic material according to embodiments exhibits a remanence that nevertheless provides the necessary counteracting force to counteract a torque on the SMT component by unequal surface tension forces between the solder deposits on the substrate bonding pads. Examples of magnetic materials that may be used as part of the magnetic layer according to a preferred embodiment may include any one of nickel or ferronickel alloys. In the case of ferronickel alloys, their compositions may be engineered in a well known manner to obtain a specific remanence according to application needs.

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